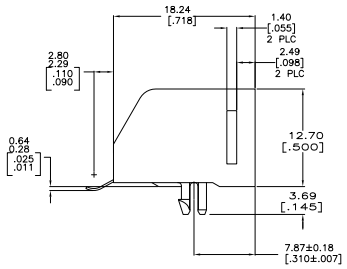
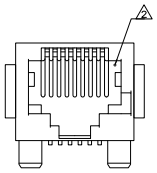
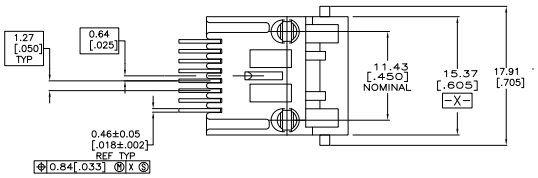
THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION
© COPYRIGHT – BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.

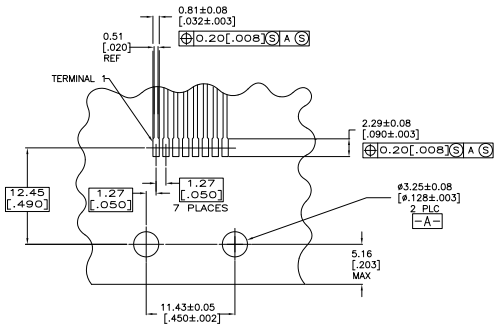
LOC	DIST	REVISIONS					
AA	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			B	ECO-07-019869	27AUG2007	LAM	PR



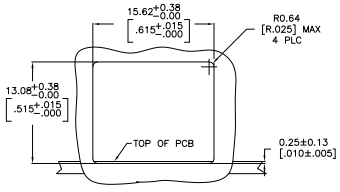


1. MATERIAL: HOUSING – HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK.
   TERMINAL – 0.36 [.014] THICK PHOS–BRONZE PLATE WITH 1.27μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
4. SNAP–IN RETENTION FEATURE ACCOMMODATES 1.45–1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.





RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE



RECOMMENDED
PANEL CUTOUT

NUMBER OF TERMINALS	PART NO
8	5555078–1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± – ; 1 PLC ± – ; 2 PLC ± – ; 3 PLC ± – ; 4 PLC ± – ; ANGLES ± –

MATERIAL: SEE NOTE 1

FINISH: SEE NOTE 1

DWN: G. ATTADIA – DOCKS
CHK: J. WESTMAN
APVD: S. FLICKINGER
PRODUCT SPEC: 108–1163
APPLICATION SPEC: 114–6040
WEIGHT: –

Tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105–3608

NAME: MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT, KEYED, WITH PANEL STOPS

SIZE: A1 | CAGE CODE: – | DRAWING NO: C=5555078 | RESTRICTED TO: –

CUSTOMER DRAWING | SCALE: 4:1 | SHEET 1 OF 1 | REV: B

AMP 4805 REV 31MAR2000

Downloaded from Elcodis.com electronic components distributor